

## PATENT ASSIGNMENT COVER SHEET

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<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
NIPUN DEV	01/27/2015
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SAP SE
<b>Street Address:</b>	DIETMAR-HOPP-ALLEE 16
<b>City:</b>	WALLDORF
<b>State/Country:</b>	GERMANY
<b>Postal Code:</b>	D-69190
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	14525689
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	11884/541201
<b>NAME OF SUBMITTER:</b>	SAMANTHA CHAN
<b>SIGNATURE:</b>	/Samantha Chan/
<b>DATE SIGNED:</b>	02/19/2015
<b>Total Attachments: 1</b>	
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## ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned hereby sell, assign, and transfer to SAP SE, a corporation of Europe, having a principal place of business at Dietmar-Hopp-Allee 16, D-69190 Walldorf, Germany ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all foreign countries, in and to any and all inventions and discoveries that are disclosed in the United States Patent Application entitled:

**SUPPORTABILITY FRAMEWORK FOR MOBILE SOFTWARE APPLICATIONS**

the specification of which is attached hereto unless the following is entered:


Filed on	as United States Application Number or PCT International Application Number	and was amended on (if applicable)
October 28, 2014	14/525,689	

and in and to said United States Patent Application and all provisional, divisional, continuing, substitute, renewal, reissue, and other patent applications that have been or shall be filed in the United States or any foreign country on any of said inventions and discoveries; and in and to all original and reissued patents that have been or shall be issued in the United States or any foreign country on said inventions and discoveries; and in and to all rights of priority resulting from the filing of said United States Patent Application;

agree that said Assignee may apply for and receive a patent or patents for said inventions and discoveries in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all provisional, divisional, continuing, substitute, renewal, reissue, and other patent applications on any and all said inventions and discoveries; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and representatives all facts known to the undersigned relating to said inventions and discoveries and the history thereof; and generally assist said Assignee, its successors, assigns, or representatives in securing and maintaining proper patent protection for said inventions and discoveries and for vesting title to said inventions and discoveries, and all applications for patents and all patents on said inventions and discoveries, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Inventor: Nipun Dev

Inventor Signature 	Date 27th January 2015
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Assignment Document Return Address:  
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